

14th IEEE/ACM International Workshop on System-Level Interconnect Prediction (SLIP 2012)

June 3, 2012

Moscone Center, San Francisco, California.

Co-located with the 49th IEEE/ACM Design Automation Conference

Co-sponsored by ACM SIGDA and the IEEE Computer Society

<http://www.sliponline.org>

The 14th International Workshop of System Level Interconnect Prediction (SLIP) will be co-located with the 49th IEEE/ACM Design Automation Conference on June 3, 2012 at the Moscone Center, San Francisco, California. The general technical scope of the workshop is the design, analysis and prediction of interconnect and communication fabrics in electronic systems. The organizing committee invites original contributions to the workshop. These contributions include papers, tutorials, panels, and special sessions. Regular papers will be double blind reviewed. Submissions with author information will be rejected. We accept papers based on novelty and contributions. The accepted papers will be published in the proceedings of SLIP 2012, which will also be included in the ACM Digital Library. Note that ACM will hold the copyright for SLIP 2012 proceedings. Authors of accepted papers must sign an ACM copyright release form for their papers.

Representative technical topics include, but are not limited to:

1. Interconnect prediction and optimization at various IC design stages
2. Interconnect design challenges and system-level NoC design
3. Design and analysis of power and clock networks
4. Interconnect architecture of structural designs and FPGAs
5. Interconnect fabrics of many-core architectures
6. Design-for-manufacturing (DFM) techniques for interconnects
7. High speed chip-to-chip interconnect design
8. Design and analysis of chip-package interfaces
9. Interconnect topologies of multiprocessor systems
10. 3D interconnect design and prediction, including TSV architecture and monolithic 3D stacking
11. Emerging interconnect technologies, e.g., RF interconnects, photonic networks, carbon-based interconnects, etc.
12. Synergies between chip communication networks and networks arising in other contexts such as social networks, system biology, etc.

Workshop themes:

Keynotes

Regular paper sessions

Paper discussion panels

Interactive poster sessions

Panels on hot research topics

Embedded tutorials and invited talks

Important dates:

Abstract Registration Due: Feb. 27, 2012
Submission Deadline: Mar. 5, 2012
Notification Due: Apr. 6, 2012
Final Version Due: Apr. 23, 2012

Authors are invited to submit papers of up to 8 pages, double-columned, 9pt or 10pt font in ACM proceedings format (<http://www.acm.org/sigs/publications/proceedings-templates>). The papers should be in the PDF format. Authors should submit papers electronically at the following link: <https://www.easychair.org/conferences/?conf=slip2012>.

More details about SLIP 2012, including submission guidelines, travel information, and registration can be found online at: www.SLIPonline.org

Organization Committee:

General Chair: Deming Chen, Univ. of Illinois at Urbana-Champaign, USA

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